

CUSHION FOR PACKING DISKS SUCH AS SEMICONDUCTOR WAFERS

ABSTRACT OF THE DISCLOSURE

A cushion device (40) for packing disks (22) such as semiconductor wafers has a base (42) that is selectively secured within a container (20). The cushion (40) includes a plurality of cushion members (60) each having two ends supported by the base (42). In a disclosed example, the cushion members (60) have a stepped configuration between the two ends. Angles between adjacent generally linear portions of the stepped configuration change as the cushion members flex responsive to engaging a semiconductor wafer within the container. A disclosed example includes a contacting portion (90) near a vertex (92) between two adjacent linear portions of a cushion member (60). One example has contacting portions (90) of aligned cushion members spaced at an angle between about 65° and about 180°.

Figure 1

20